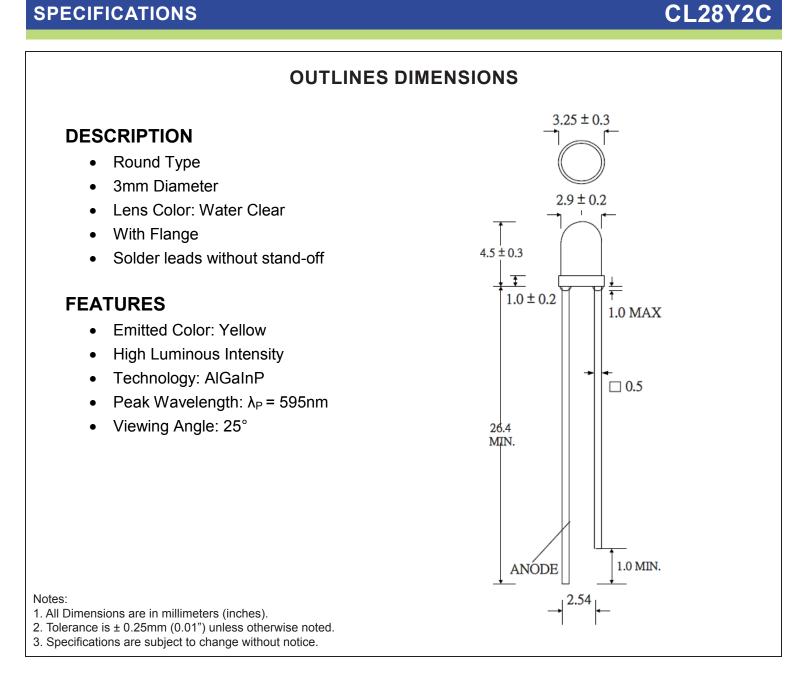


SPECIFICATIONS



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CL28Y2C	InGaAIP	Yellow	Water Clear	25°



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ABSOLUTE MAXIMUM RATINGS

Parameter Symbol Max Rating Unit 120 **Power Dissipation** PD mW 100 **Pulse Current Forward Current** IFP mA 20 **Continuous Forward Current** IF mA V **Reverse Voltage** VR 5 **Operating Temperature Range** TOPR -40~+85 °C Storage Temperature Range °C Tstg -40~+85 IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

Value Parameter Test Condition Unit Symbol Min Тур Max 1200 1800 Luminous Intensity Iv I_F = 20mA _ mcd I⊧ = 20mA 2.0 2.4 V **Forward Voltage** VF 10 $V_R = 5V$ _ Reverse Leakage Current IR _ μA 25 $2\theta 1/2$ I_F = 20mA Viewing Angle deg _ Peak Wavelength I_F = 20mA 595 λP _ nm _ **Dominant Wavelength** λD I_F = 20mA 592 nm _ _ I_F = 20mA Spectral Line half-width Δλ 20 _ nm _

*Tolerance of viewing angle: -10 / +5 deg.



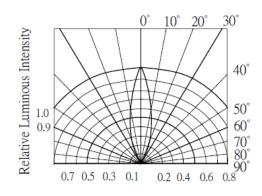
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(TA=25°C)

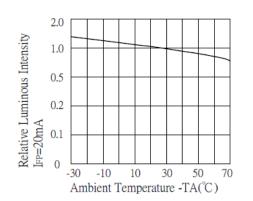
(TA=25°C)



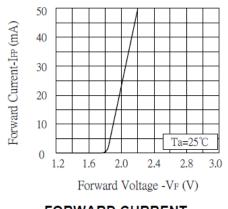
OPTICAL CHARACTERISTIC CURVES



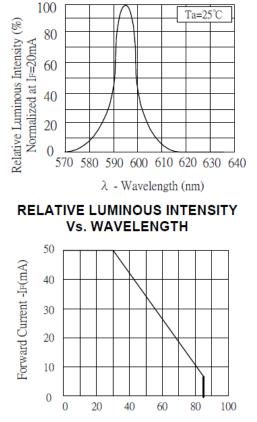
RADIATION DIAGRAM



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

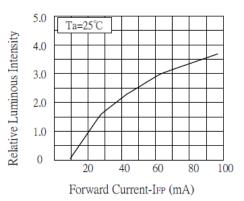


FORWARD CURRENT Vs. FORWARD VOLTAGE



Ambient Temperature -TA(°C)

MAX FORWARD CURRENT Vs. AMBIENT TEMPERATURE



LUMINOUS INTENSITY Vs. FORWARD CURRENT



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SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering				
Temperature Soldering Time Position	3mm Series	Others		
	300 °C Max	350 °C Max		
	3 Second Max	3 Second Max		
FOSILION	No closer than 3mm from the	No closer than 3mm from the		
	base of the epoxy	base of the epoxy		

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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